BFR92AW

NPN 5 GHz wideband transistor

Rev. 03 — 12 March 2008 Product data sheet

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NPN 5 GHz wideband transistor — BFR92AW

FEATURES

- High power gain
- Gold metallization ensures excellent reliability
- SOT323 (S-mini) package.

APPLICATIONS

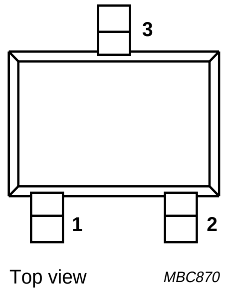
It is designed for use in RF amplifiers, mixers and oscillators with signal frequencies up to 1 GHz.

DESCRIPTION

Silicon NPN transistor encapsulated in a plastic SOT323 (S-mini) package. The BFR92AW uses the same crystal as the SOT23 version, BFR92A.

PINNING

PIN	DESCRIPTION
1	base
2	emitter
3	collector



Marking code: P2.

Fig.1 SOT323

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter	–	–	20	V
V_{CEO}	collector-emitter voltage	open base	–	–	15	V
I_C	collector current (DC)		–	–	25	mA
P_{tot}	total power dissipation	up to T_s = 93 °C; note 1	–	–	300	mW
h_{FE}	current gain	I_C = 15 mA; V_{CE} = 10 V	65	90	135	
C_{re}	feedback capacitance	I_C = 0; V_{CE} = 10 V; f = 1 MHz; T_{amb} = 25 °C	–	0.35	–	pF
f_T	transition frequency	I_C = 15 mA; V_{CE} = 10 V; f = 500 MHz	3.5	5	–	GHz
G_{UM}	maximum unilateral power gain	I_C = 15 mA; V_{CE} = 10 V; f = 1 GHz; T_{amb} = 25 °C	–	14	–	dB
		I_C = 15 mA; V_{CE} = 10 V; f = 2 GHz; T_{amb} = 25 °C	–	8	–	dB
F	noise figure	I_C = 5 mA; V_{CE} = 10 V; f = 1 GHz; $\Gamma_s = \Gamma_{opt}$	–	2	–	dB
T_j	junction temperature		–	–	150	°C

Note

1. T_s is the temperature at the soldering point of the collector pin.

LIMITING VALUES

In accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter	–	20	V
V_{CEO}	collector-emitter voltage	open base	–	15	V
V_{EBO}	emitter-base voltage	open collector	–	2	V
I_C	collector current (DC)		–	25	mA
P_{tot}	total power dissipation	up to T_s = 93 °C; see Fig.2; note 1	–	300	mW
T_{stg}	storage temperature		–65	+150	°C
T_j	junction temperature		–	150	°C

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j\text{-}s}$	thermal resistance from junction to soldering point	up to T_s = 93 °C; note 1	190	K/W

Note to the Limiting values and Thermal characteristics

1. T_s is the temperature at the soldering point of the collector pin.

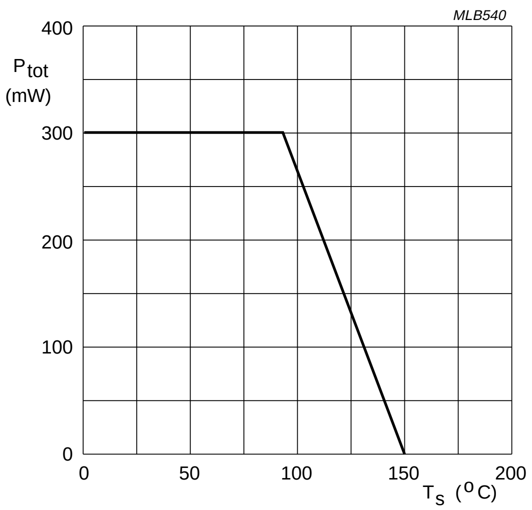


Fig.2 Power derating curve

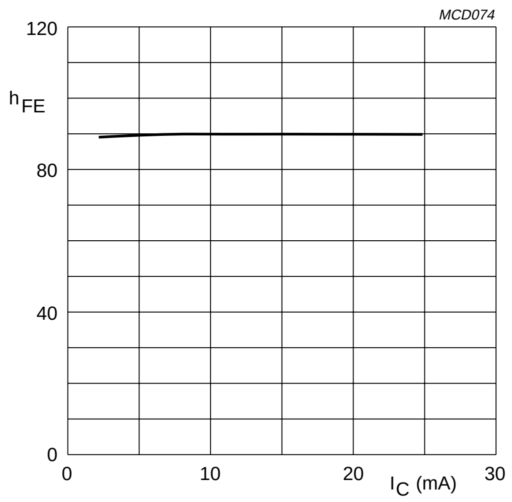
CHARACTERISTICS

T_j = 25 °C (unless otherwise specified).

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I_{CBO}	collector leakage current	$I_E = 0$; $V_{CB} = 10$ V	–	–	50	nA
h_{FE}	DC current gain	$I_C = 15$ mA; $V_{CE} = 10$ V	65	90	135	
C_c	collector capacitance	$I_E = i_e = 0$; $V_{CB} = 10$ V; f = 1 MHz	–	0.6	–	pF
C_e	emitter capacitance	$I_C = i_c = 0$; $V_{EB} = 0.5$ V; f = 1 MHz	–	0.9	–	pF
C_{re}	feedback capacitance	$I_C = 0$; $V_{CE} = 10$ V; f = 1 MHz	–	0.35	–	pF
f_T	transition frequency	$I_C = 15$ mA; $V_{CE} = 10$ V; f = 500 MHz	3.5	5	–	GHz
G_{UM}	maximum unilateral power gain; note 1	$I_C = 15$ mA; $V_{CE} = 10$ V; f = 1 GHz; $T_{amb} = 25$ °C	–	14	–	dB
		$I_C = 15$ mA; $V_{CE} = 10$ V; f = 2 GHz; $T_{amb} = 25$ °C	–	8	–	dB
F	noise figure	$I_C = 5$ mA; $V_{CE} = 10$ V; f = 1 GHz; $\Gamma_s = \Gamma_{opt}$	–	2	–	dB
		$I_C = 5$ mA; $V_{CE} = 10$ V; f = 2 GHz; $\Gamma_s = \Gamma_{opt}$	–	3	–	dB

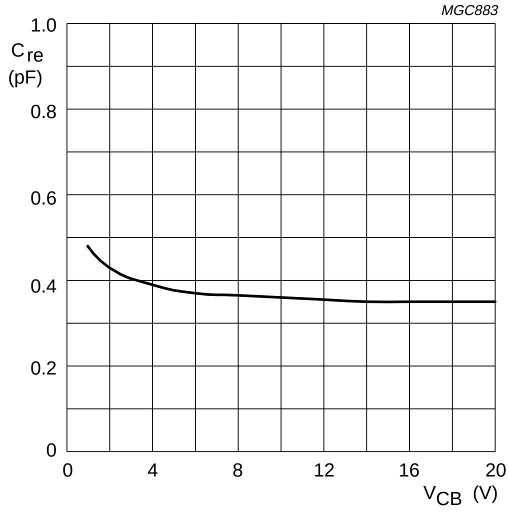
Note

1. G_{UM} is the maximum unilateral power gain, assuming s_{12} is zero and $G_{UM} = 10\ \log\dfrac{|s_{21}|^2}{(1-|s_{11}|^2)\ (1-|s_{22}|^2)}$ dB.



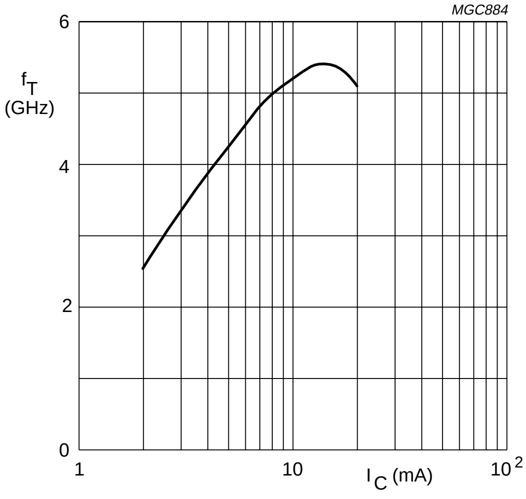
V_{CE} = 10 V.

Fig.3 DC current gain as a function of collector current; typical values.



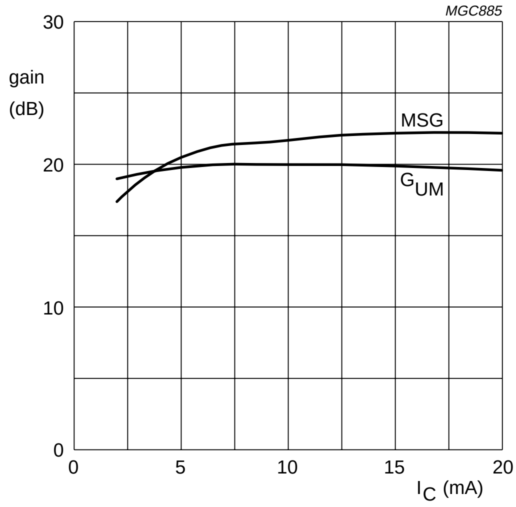
I_C = 0; f = 1 MHz.

Fig.4 Feedback capacitance as a function of collector-base voltage; typical values.



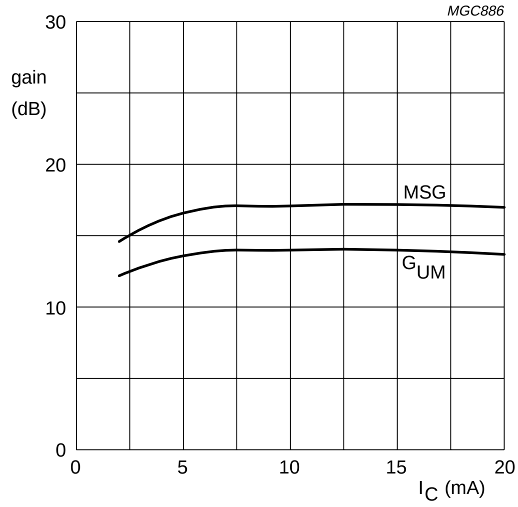
V_{CE} = 5 V; f = 500 MHz; T_{amb} = 25 °C.

Fig.5 Transition frequency as a function of collector current; typical values.



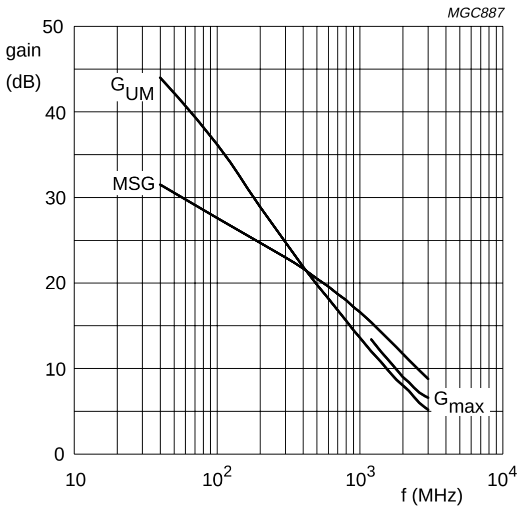
V_{CE} = 10 V; f = 500 MHz.

Fig.6 Gain as a function of collector current; typical values.



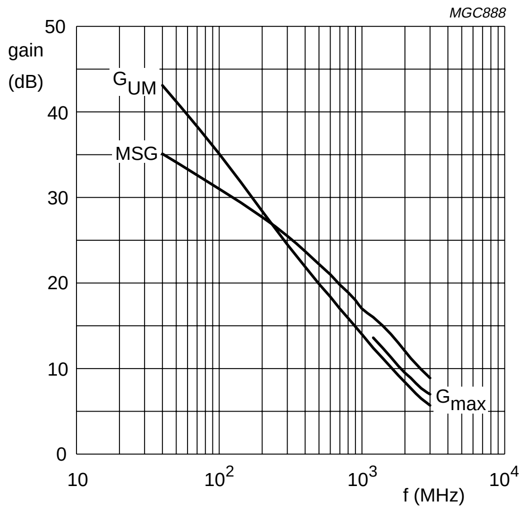
V_{CE} = 10 V; f = 1 GHz.

Fig.7 Gain as a function of collector current; typical values.



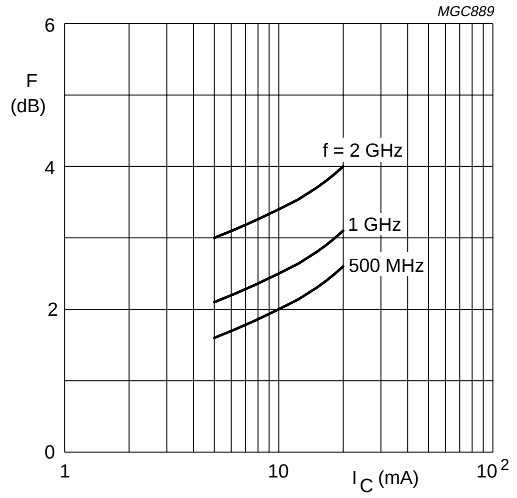
V_{CE} = 10 V; I_C = 5 mA.

Fig.8 Gain as a function of frequency; typical values.



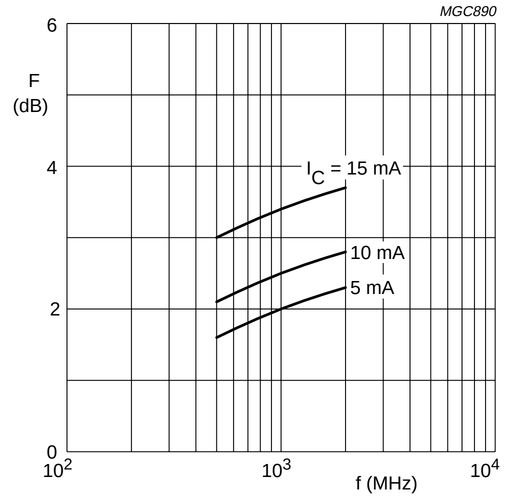
V_{CE} = 10 V; I_C = 15 mA.

Fig.9 Gain as a function of frequency; typical values.



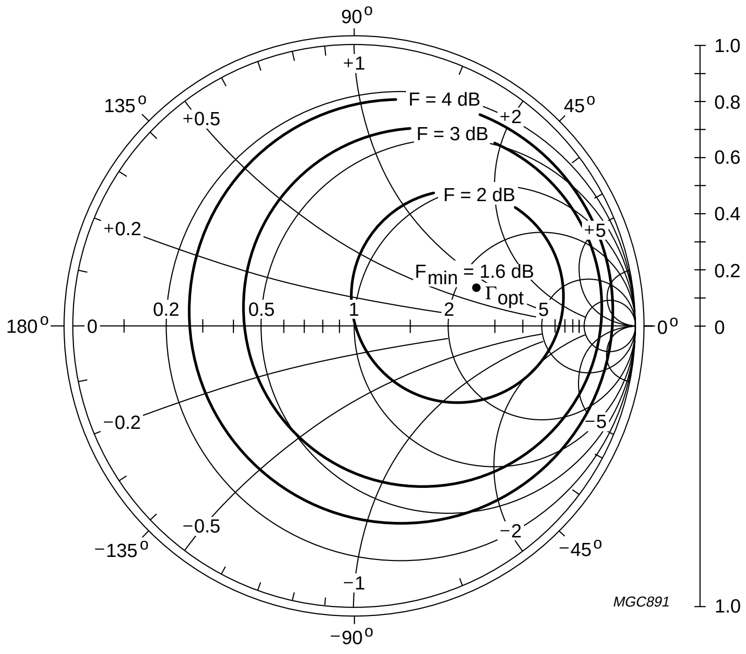
V_{CE} = 10 V.

Fig.10 Minimum noise figure as a function of collector current; typical values.



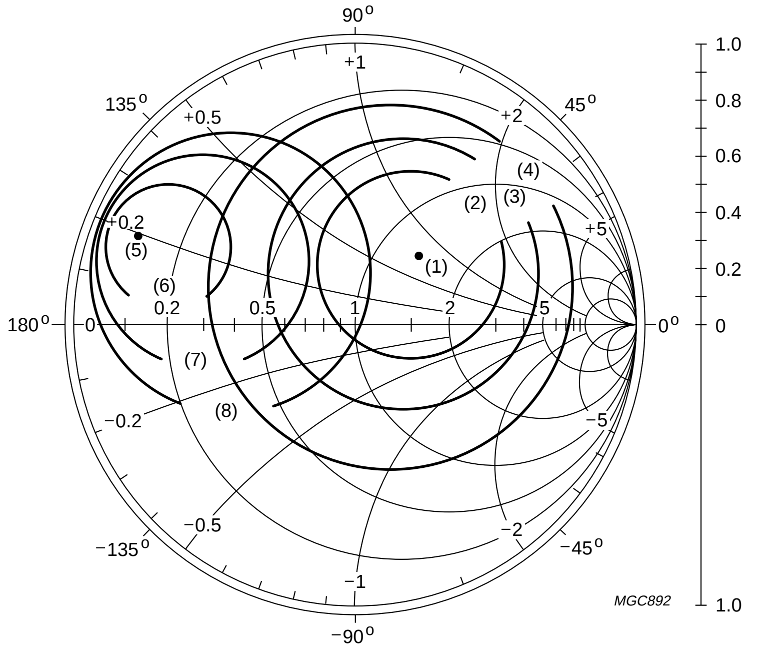
V_{CE} = 10 V.

Fig.11 Minimum noise figure as a function of frequency; typical values.



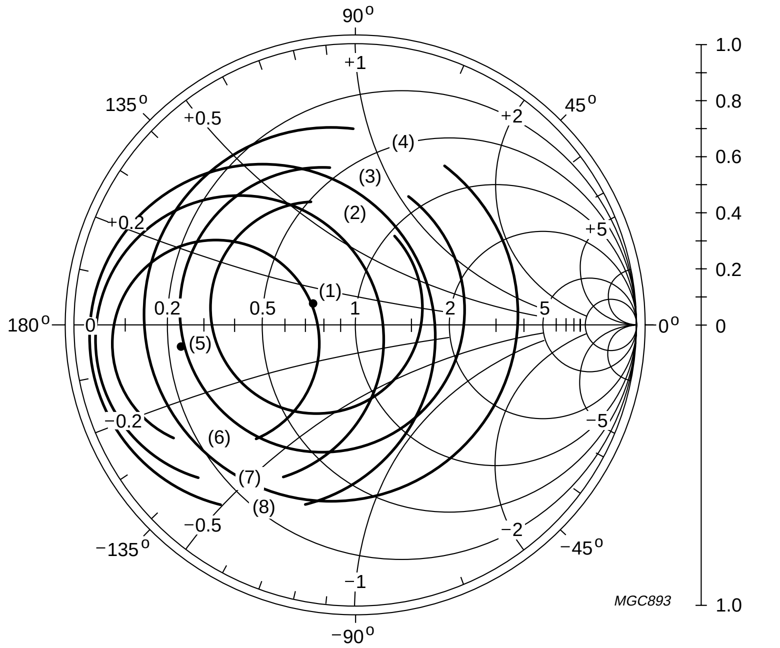
f = 500 MHz; V_{CE} = 10 V; I_C = 5 mA; Z_o = 50 Ω.

Fig.12 Common emitter noise figure circles; typical values.



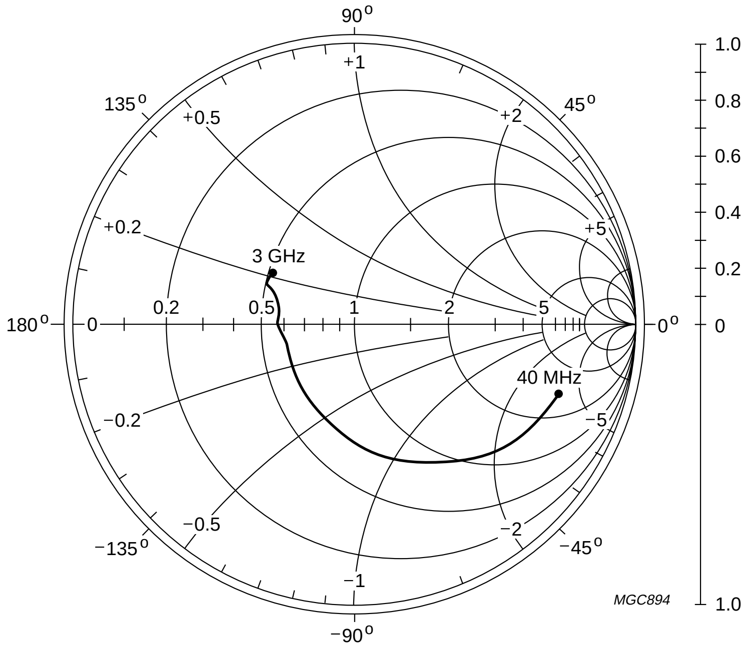
(1) Γ_{opt}; F_{min} = 2.1 dB.
(2) F = 2.5 dB.
(3) F = 3 dB.
(4) F = 4 dB.
(5) Γ_{ms}; G_{max} = 15.7 dB.
(6) G = 15 dB.
(7) G = 14 dB.
(8) G = 13 dB.
f = 1 GHz; V_{CE} = 10 V; I_C = 5 mA; Z_o = 50 Ω.

Fig.13 Common emitter noise figure circles; typical values.



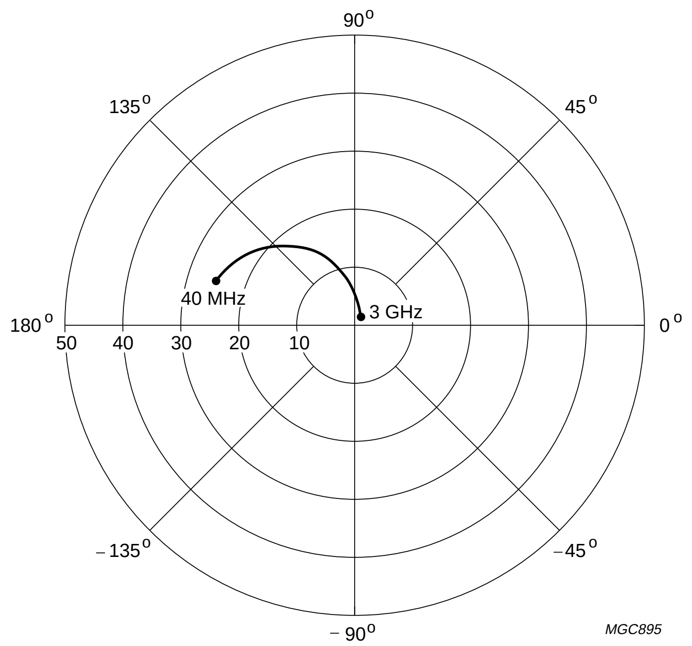
(1) Γ_{opt}; F_{min} = 3 dB.
(2) F = 3.5 dB.
(3) F = 4 dB.
(4) F = 5 dB.
(5) Γ_{ms}; G_{max} = 9.1 dB.
(6) G = 8 dB.
(7) G = 7 dB.
(8) G = 6 dB.
f = 2 GHz; V_{CE} = 10 V; I_C = 5 mA; Z_o = 50 Ω.

Fig.14 Common emitter noise figure circles; typical values.



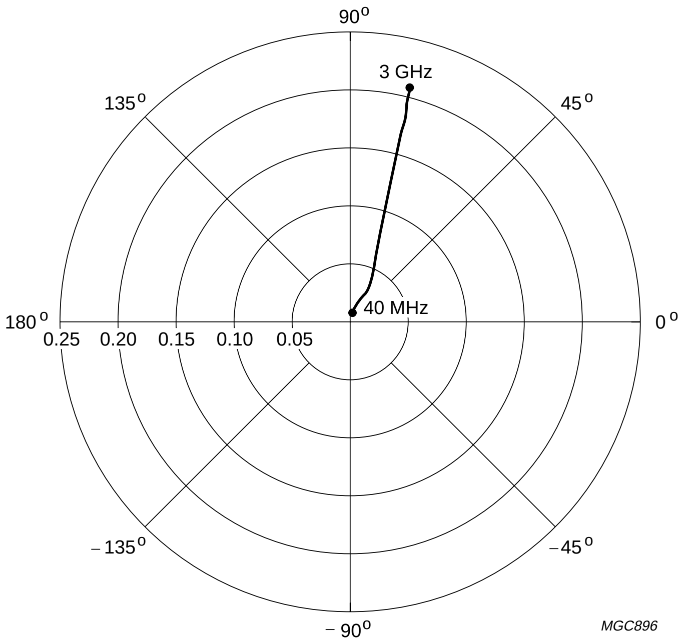
V_{CE} = 10 V; I_C = 15 mA; Z_o = 50 Ω.

Fig.15 Common emitter input reflection coefficient (s_{11}); typical values.



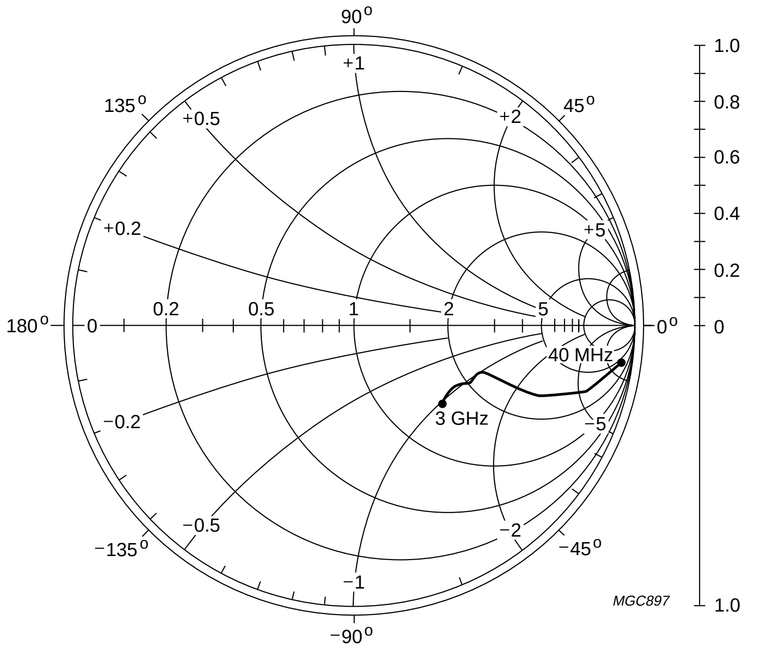
V_{CE} = 10 V; I_C = 15 mA.

Fig.16 Common emitter forward transmission coefficient (s_{21}); typical values.



V_{CE} = 10 V; I_C = 15 mA.

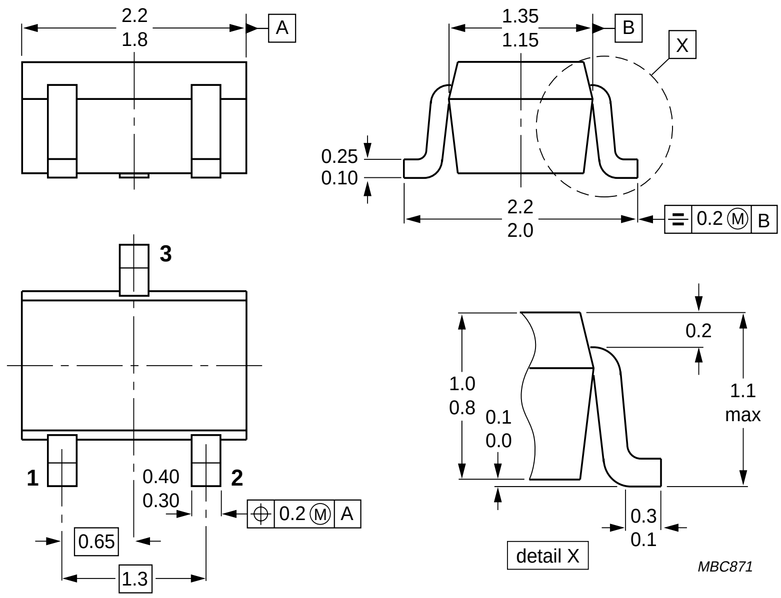
Fig.17 Common emitter reverse transmission coefficient (s_{12}); typical values.



V_{CE} = 10 V; I_C = 15 mA; Z_o = 50 Ω.

Fig.18 Common emitter output reflection coefficient (s_{22}); typical values.

PACKAGE OUTLINE



Dimensions in mm.

Fig.19 SOT323.

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Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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Revision history

Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BFR92AW_N_3	20080312	Product data sheet	-	BFR92AW_2
Modifications:	• Quick reference data and Characteristics Table; DC current gain value changed			
BFR92AW_2	19950918	Product specification	-	BFR92AW_1
BFR92AW_1	19921001	-	-	-

Date of release: 12 March 2008

Document identifier: BFR92AW_N_3